

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03755	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01126	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03755	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.46142	99.77	400.0777
<b>Subtotal</b>				<b>37.54778</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84502	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.92712	10.0	63.3
	Filler	Silica fused	60676-86-0	50.38051	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11854	0.2	1.266
<b>Subtotal</b>				<b>59.27119</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34088	100.0	25
			<b>Subtotal</b>	<b>2.34088</b>	<b>100</b>	<b>25</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00331	2.0	0.03538
		Silver (Ag)	7440-22-4	0.00414	2.5	0.04422
		Lead (Pb)	7439-92-1	0.15819	95.5	1.68939
<b>Subtotal</b>				<b>0.16564</b>	<b>100</b>	<b>1.76899</b>
Die		Lead Dioxide (PbO2)	1309-60-0	0.00401	0.93	0.04278
	Doped silicon	Silicon (Si)	7440-21-3	0.42672	99.07	4.55722
<b>Subtotal</b>				<b>0.43073</b>	<b>100</b>	<b>4.6</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.24379	100.0	2.6036
			<b>Subtotal</b>	<b>0.24379</b>	<b>100</b>	<b>2.6036</b>
<b>Total</b>				<b>100.00001</b>	<b>100</b>	<b>1067.97259</b>

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